MUR860

Ultrafast power diode

Rev.02 - 19 March 2024 Product data sheet

1. General description

Ultrafast power diode in a SMC package.

2. Features and benefits

- Fast switching
- SMC package
- High voltage capability
- Low forward voltage drop
- Low leakage current
- Low thermal resistance
- Soft recovery characteristic

3. Applications

- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)
- use in switching power supplies, inverters and as free wheeling diodes
- High frequency switched-mode power supplies

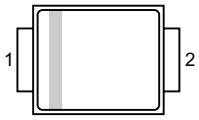
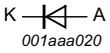
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute maximum rating				
V_{RRM}	repetitive peak reverse voltage		600	V
$I_{F(AV)}$	average forward current	δ = 0.5; square-wave pulse; $T_{lead} \leq 95$ °C; Fig. 1; Fig. 2; Fig. 3	8	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{lead} \leq 95$ °C; square-wave pulse	16	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	180	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	200	A

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
MUR860	SMC	MUR860J	Reel	3000	SMCS	16-Aug-2017
		MUR860,118				

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: S	Assembly factory: E
MUR860	860JS	860JE

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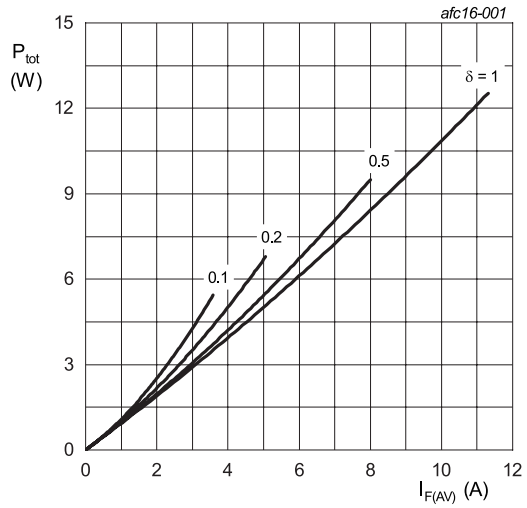
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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

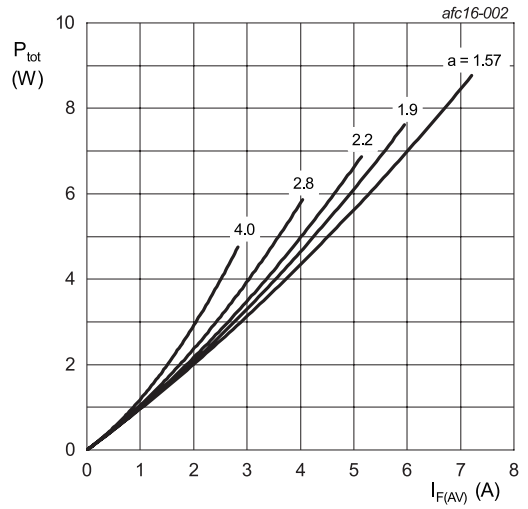
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	δ = 0.5; square-wave pulse; $T_{lead} \leq 95$ °C; Fig. 1; Fig. 2; Fig. 3	8	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{lead} \leq 95$ °C; square-wave pulse	16	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	180	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	200	A
T_{stg}	storage temperature		-65 to 175	°C
T_j	junction temperature		175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$

V_o = 0.918 V; R_s = 0.0168 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)} / I_{F(AV)}$

V_o = 0.918 V; R_s = 0.0168 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

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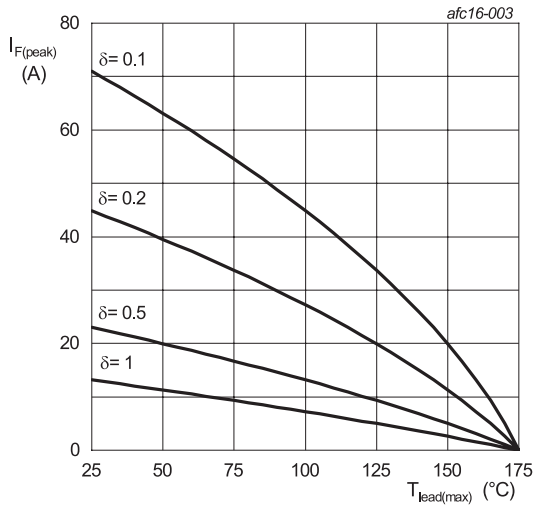


Fig. 3. Forward current as a function of lead temperature; maximum values

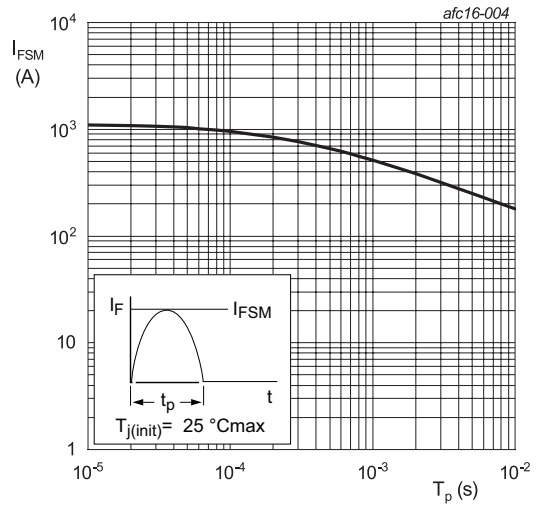


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j\text{-}lead)}$	thermal resistance from junction to lead	Fig. 5		-	-	10	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	in free air		-	75	-	K/W

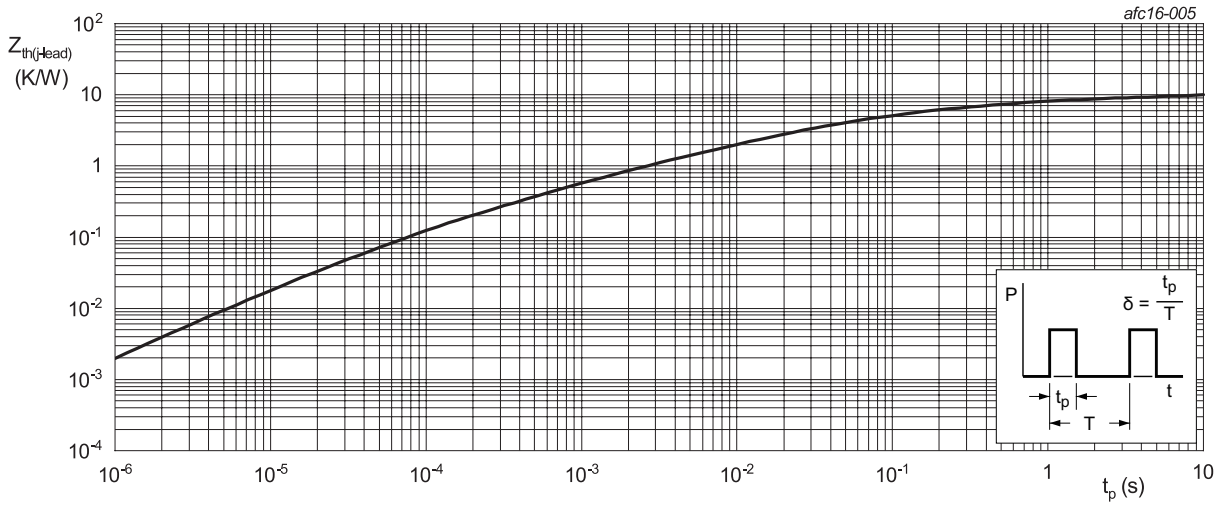


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse duration

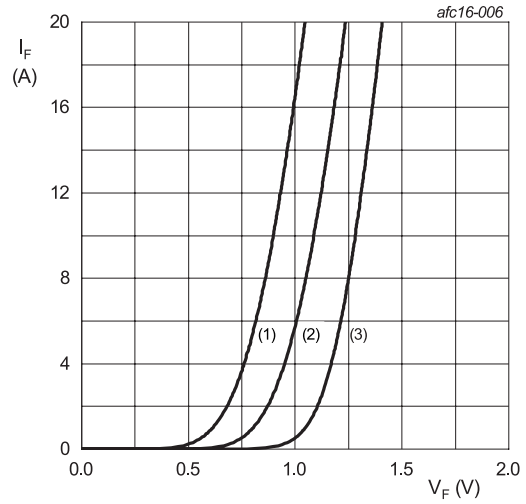
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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	I_F = 8 A; T_j = 25 °C; Fig. 6		-	-	1.25	V
		I_F = 8 A; T_j = 150 °C; Fig. 6		-	-	1.05	V
I_R	reverse current	V_R = 600 V; T_j = 25 °C		-	-	10	µA
		V_R = 600 V; T_j = 150 °C		-	-	400	µA
Dynamic characteristics							
Q_r	reverse charge	I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 25 °C; Fig. 7		-	494	-	nC
		I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 125 °C; Fig. 7		-	983	-	nC
t_{rr}	reverse recovery time	I_F = 1 A; V_R = 30 V; dI_F/dt= 50 A/us; T_j = 25 °C; Fig. 7		-	66	90	ns
		I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 25 °C; Fig. 7		-	93	-	ns
		I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 125 °C; Fig. 7		-	130	-	ns
I_{RM}	peak reverse recovery current	I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 25 °C; Fig. 7		-	11	-	A
		I_F = 8 A; V_R = 400 V; dI_F/dt = 200 A/us; T_j = 125 °C; Fig. 7		-	15	-	A



V_o = 0.918 V; R_s = 0.0168 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage

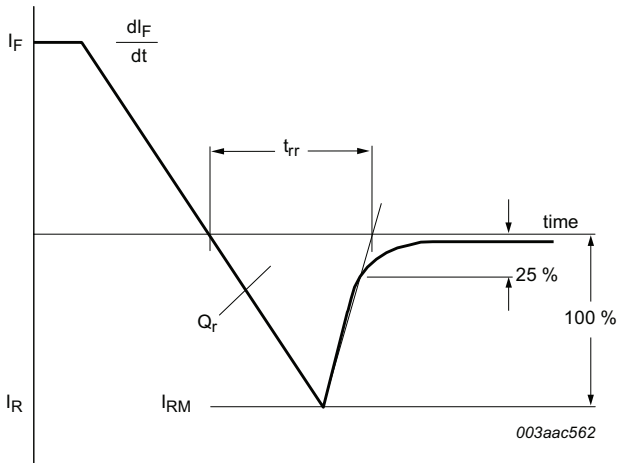
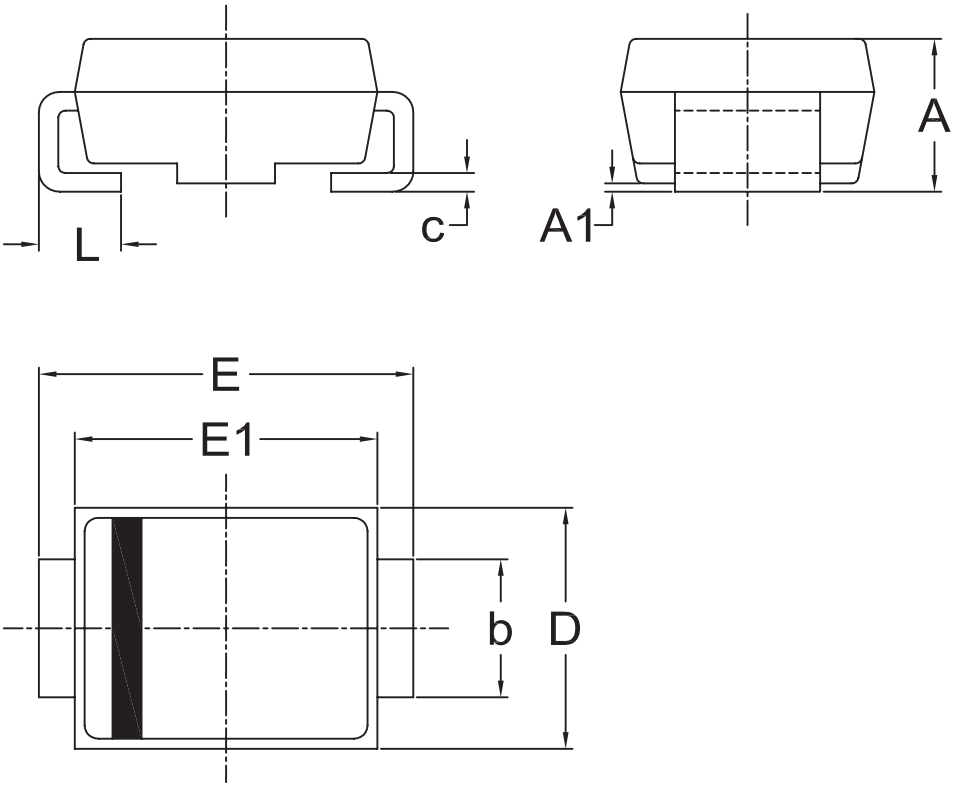


Fig. 7. Reverse recovery definitions; ramp recovery

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11. Package outline



UNIT		A	A1	b	c	D	E	E1	L
mm	Max	2.40	0.22	3.18	0.31	6.22	8.13	7.11	1.52
	Min	2.01	0.05	2.92	0.15	5.59	7.70	6.60	0.76

Remark: Dimensions D and E1 do not include mold flash.

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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13. Contents

1. General description 1
2. Features and benefits 1
3. Applications 1
4. Quick reference data 1
5. Pinning information 2
6. Ordering information 2
7. Marking 2
8. Limiting values 3
9. Thermal characteristics 5
10. Characteristics 6
11. Package outline 7
12. Legal information 8
13. Contents 10

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